

Date Created : 2008/08/20
Date Issued On : 2008/09/17
PCN# : Q3083402

INFORMATION ONLY NOTIFICATION

This is to inform you that a minor change is being made to the following product(s). This notification is for your information only.

If you have any questions concerning this change, please contact:

Technical Contact:

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Phone:

PCN Originator:

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Phone:

Implementation of change:

Expected 1st Device Shipment Date: 2008/10/26

Earliest Year/Work Week of Changed Product: 0844

Change Type Description: Bond Wire Diameter

Description of Change (From): 15mil * 1ea per chip(2chip), total 15mil 2ea

Description of Change (To): 20mil * 2ea per chip(2chip), total 20mil 4ea

Reason for Change : Resolving Vf issued observed when affected devices were change from 2x 20mils Al-wire per die to 1x 15mils Al-wire per die.

Product Id Description : Some Schottky diodes devices packaged in TO220 & TO220F. The products affected by this change are listed below in the "Affected FSIDs" section

Affected FSIDs :

FYP1004DNTU	FYP1010DNTU	FYP1045DNTU
FYP1504DNTU	FYP1545DNTU	FYP2004DNTU
FYP2006DNTU	FYP2010DNTU	FYP2045DNTU
FYPF1545DNTU	FYPF2004DNTU	FYPF2006DNTU
FYPF2010DNTU	FYPF2045DNTU	MBR20S100CT
MBR20S100CTTU	MBRP1545NTU	MBRP2045NTU
MBRP3010NTU	MBRP3045NTU	MBRP3045NTU_F080